

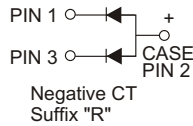
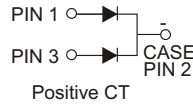


FEATURES

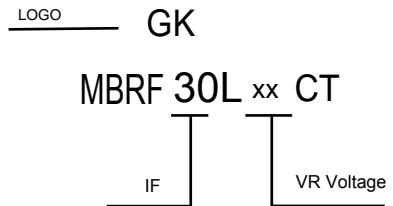
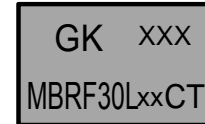
- * Low forward voltage drop
- * High current capability
- * High reliability
- * High surge current capability
- * Good for switching mode application

MECHANICAL DATA

- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Lead: Axial leads, solderable per MIL-STD-202, method 208 guaranteed
- * Polarity: Color band denotes cathode end
- * Mounting position: Any



VOLTAGE RANGE
45 to 200 Volts
CURRENT
30.0 Ampere



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

| TYPE NUMBER | MBRF30L45CT | MBRF30L60CT | MBRF30L100CT | MBRF30L150CT | MBRF30L200CT | UNITS |
|--|-------------|-------------|--------------|--------------|--------------|-------|
| Maximum Recurrent Peak Reverse Voltage | 45 | 60 | 100 | 150 | 200 | V |
| Maximum RMS Voltage | 45 | 60 | 100 | 150 | 200 | V |
| Maximum DC Blocking Voltage | 32 | 42 | 70 | 105 | 140 | V |
| Maximum Average Forward Rectified Current | 30 | | | | | A |
| Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method) | 200 | | | | | A |
| Maximum Instantaneous Forward Voltage at 30A | 0.5 | 0.58 | 0.75 | 0.88 | | V |
| Maximum DC Reverse Current Ta=25°C | 0.2 | | | | | mA |
| at Rated DC Blocking Voltage Ta=100°C | 50 | | | | | mA |
| Typical Junction Capacitance (Note1) | 500 | | | | | pF |
| Typical Thermal Resistance RθJC (Note 2) | 2.5 | | | | | °C/W |
| Operating Temperature Range Tj | -65 — +150 | | | | | °C |
| Storage Temperature Range Tstg | -65 — +150 | | | | | °C |

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance Junction to Case.

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

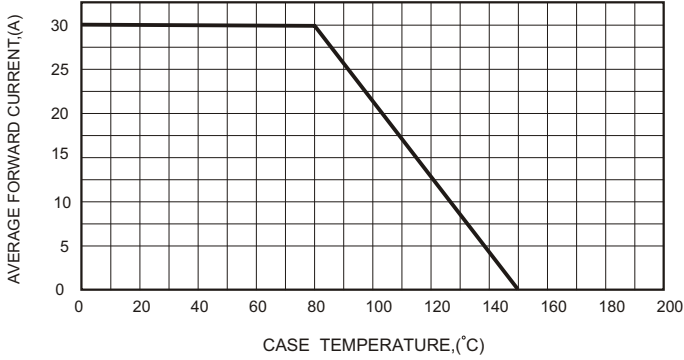


FIG.2-TYPICAL FORWARD CHARACTERISTICS

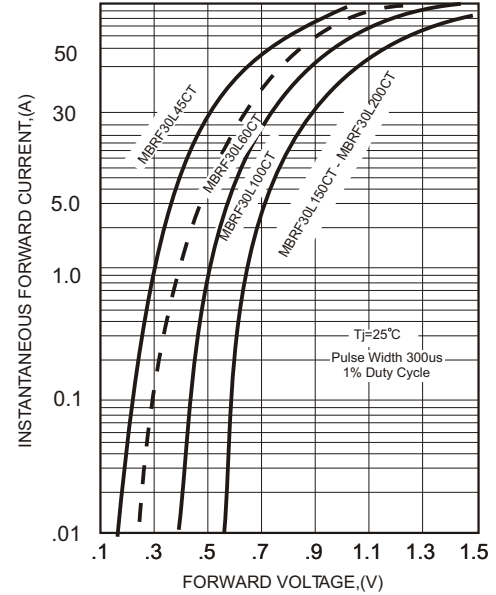


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

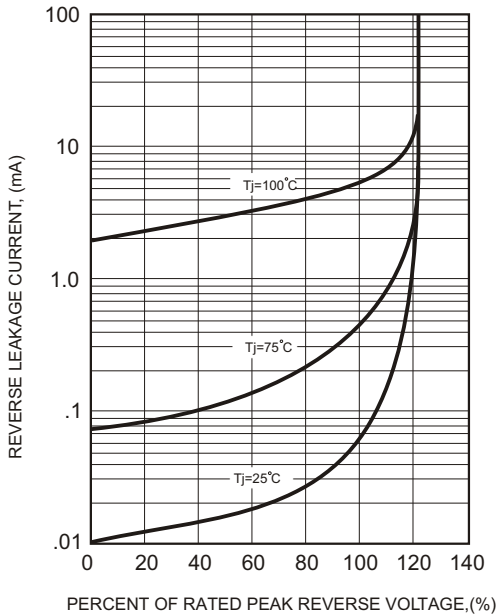


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

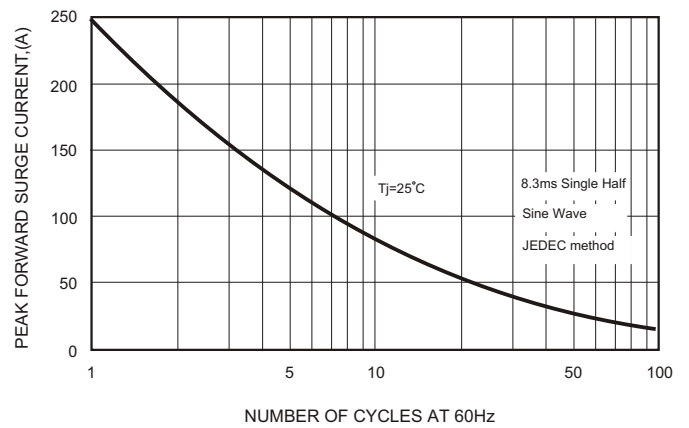
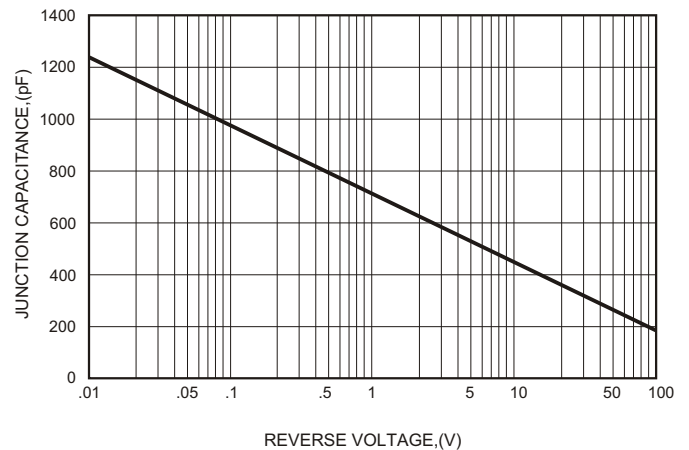


FIG.5-TYPICAL JUNCTION CAPACITANCE



Soldering parameters

| Reflow Condition | | Pb-Free assembly (see as below) |
|---|-----------------------------------|------------------------------------|
| Pre Heat | -Temperature Min ($T_{s(min)}$) | +150 °C |
| | -Temperature Max($T_{s(max)}$) | +200 °C |
| | -Time (Min to Max) (ts) | 60-180 secs. |
| Average ramp up rate (Liquid us Temp (T_L) to peak) | | 3 °C/sec. Max |
| $T_{s(max)}$ to T_L - Ramp-up Rate | | 3 °C/sec. Max |
| Reflow | -Temperature(T_L)(Liquid us) | +217 °C |
| | -Temperature(t_L) | 60-150 secs. |
| Peak Temp (T_P) | | +260(+0/-5) °C |
| Time within 5 °C of actual Peak Temp (t_p) | | 30 secs. Max |
| Ramp-down Rate | | 6 °C/sec. Max |
| Time 25 °C to Peak Temp (T_P) | | 8 min. Max |
| Do not exceed | | +260 °C |



Package Dimensions & Suggested Pad Layout

